SA.31m, SA.33m, and SA.35m
Miniature Atomic Clock (MAC) SA.3Xm

Features
• High-precision atomic clock
• Small form factor (standard OCXO pinout)
• 1.5 µs typical holdover over temperature (SA.35m)
• Low power consumption
• RoHs 6/6-compliant

Applications
• Stand-alone (free-run) stable frequency source for audio equipment, LTE base stations, smart grid, and enterprise network infrastructure
• Extended holdover for CDMA and WiMAX base stations
• Stability for various other communication and transmission applications

Newly Enhanced MAC SA.3Xm Family
The Microsemi SA.3Xm marks a major step forward in the evolution of rubidium atomic clocks. Based on a new generation of atomic clock technology, the SA.3Xm family has a unique package that enables unprecedented miniaturization in a rubidium clock. It is suitable for applications requiring compact design, low power consumption, extended aging, and precision in an economical and easily adaptable package.

Smallest Commercially Available Rubidium Clock
Microsemi has leveraged the significant advances in miniaturization and integration to design the world’s first commercially available miniature atomic clock. The SA.3Xm has physical dimensions and packaging of a small ovenized crystal oscillator (OCXO), measuring 50.8 mm x 50.8 mm (2" x 2") and standing at a mere 18.3 mm (0.72"). The MAC is the world’s first commercially available rubidium coherent population trapping atomic clock. It consumes less power and has wide-spectrum temperature operation. This makes it useful for a range of timing and synchronization applications—wireless base stations, wire line network infrastructure, defense systems, and test and measurement devices. The small size of the SA.3Xm enables it to be easily mounted to a PCBA.

SA.31m
The SA.31m is targeted for applications that require an economical solution for frequency stability, such as audio equipment in studio applications. It can also be used as an independent frequency source for next generation base stations, smart grid infrastructure and Enterprise network infrastructure. It enables transition from costly TDM backhaul transport to economic and efficient Ethernet transport.

SA.33m
The SA.33m has superior aging and tempco, and better stability and phase noise than the SA.31m. The SA.33m may be deployed in existing rubidium applications such as extended holdover (for CDMA/CDMA 2000 or WiMAX).

SA.35m
The SA.35m is the premium grade of the entire SA.3Xm family. It has the best tempco and greatest performance amongst all the versions of the family. The SA.35m is suited for applications such as extended hold over for LTE-TDD base stations and other applications that require precision frequency and long hold-over. Economical for its performance level, the SA.35m delivers premium performance at an excellent price.
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MAC SA.3Xm Mechanical Diagram

**Notes:**

1. **Dimensioning and Tolerancing Per ANSI Y14.5.**
2. **Caution:** Screw penetration of more than .07 into baseplate could result in damage to this device.
3. Weight: Less than 3 oz.

**Pin No.** | **Function**
--- | ---
1 | Input Frequency Control
2 | Case Ground
3 | RF Output
4 | Ground (Supply and Signal)
5 | Input Supply (+5 VDC)
6 | Video
7 | RS-232 TX
8 | RS-232 RX

**Note:** Connect Pin 2 to GND externally. Pin 2 and Pin 4 are not connected together internally.
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Specifications

Electrical

RF Output
- Frequency: 10 MHz
- Waveform: CMOS square wave, 0 V to 5 V (max)
- Logic level: V_{OL(max)} = 0.55 V, V_{OH(min)} = 2.3 V
- Rise/fail time: <10 ns (15 pf, 1MΩ load)
- Duty cycle: 50% ± 10%

Built-in Test Equipment Output
- Format: CMOS
- Logic: 0 = Normal Operation, 1 = Alarm

Serial Communications
- Protocol: RS232
- Format: CMOS 0 V to 5 V
- Baud rate: 57600 (8, N, 1)

Power Input
- Supply voltage/current: 5 V ± 0.1 V, max current <2.8 A
- Power consumption:
  - Warm-up: 14 W max (–10 °C to 75 °C)
  - Operating: 8 W at 10 °C, 5 W at 25 °C, 5 W at 75 °C baseplate
- Voltage coefficient: <2 × 10^{-11} peak-to-peak (+5 V ± 0.1 V)

Environmental
- Operating temperature: –10 °C to 75 °C baseplate
- Magnetic field sensitivity: <±7 × 10^{-11}/Gauss (up to ±2 Gauss)
- Humidity: GR-63-CORE, issue 4, April 2012, section 4.1.2
- Vibration (operating): 7.7 g rms, at 1 hour/axis
  MIL-STD-810, figure 514.7E-1, category 24 (General Minimum Integrity Exposure) No loss of lock
- Shock (operating): 30 g, 11 ms half-sine pulse per MIL-STD-202, Method 213, Test Condition J.
- Frequency perturbation ≤4 × 10^{-9} momentary
- Storage and Transport (Non-operating)
  - Temperature: –55 °C to 100 °C
  - Vibration (non-operating, unpackaged): 10.9 g rms at 1 hour/axis per MIL-STD-810, figure 514.7E-1, Cat 24
  - Shock (non-operating, unpackaged): 50 g, 11 ms half-sine pulse per MIL-STD-202, Method 213, Test Condition A

Performance Parameters
- Warm-up time (time to <1 × 10^{-9}) <15 min (typical at 25 °C)
- Retrace: <±5 × 10^{-11} (on-off-on: 24 hours, 48 hours, 12 hours at 25 °C)
- Analog tuning
  - Range: ±1 × 10^{-8}
  - Input: 0 V–5 V into 5 kΩ
- Digital tuning
  - Range: ±2 × 10^{-8} (resolution ±1 × 10^{-12})
- Time drift in a 24 hr period (SA.35m): 1.5 μs, typical (–10 °C to 70 °C, 16 °C/hr)
- MTBF
  - Per MIL-HDBK-217F:
    - ≥20 years at 40 °C (ground, benign, GB)
    - ≥17 years at 40 °C (ground, fixed, GF)
  - Per Telcordia SR-332, Issue 1:
    - ≥20 years at 40 °C (ground, fixed, uncontrolled)
- Accuracy at shipment: <±5 × 10^{-11} (25 °C)

1At 25 °C and 5 V DC, unless otherwise specified.
Microsemi Corporation (Nasdaq: MSCC) offers a comprehensive portfolio of semiconductor and system solutions for aerospace & defense, communications, data center and industrial markets. Products include high-performance and radiation-hardened analog mixed-signal integrated circuits, FPGAs, SoCs and ASICs; power management products; timing and synchronization devices and precise time solutions, setting the world's standard for time; voice processing devices; RF solutions; discrete components; enterprise storage and communication solutions, security technologies and scalable anti-tamper products; Ethernet solutions; Power-over-Ethernet ICs and midspans; as well as custom design capabilities and services. Microsemi is headquartered in Aliso Viejo, California and has approximately 4,800 employees globally. Learn more at www.microsemi.com.

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### Phase Noise (SSB)

<table>
<thead>
<tr>
<th>Frequency</th>
<th>SA.35/SA.33m</th>
<th>SA.31m</th>
</tr>
</thead>
<tbody>
<tr>
<td>1 Hz</td>
<td>&lt;-70 dBc/Hz</td>
<td>&lt;-65 dBc/Hz</td>
</tr>
<tr>
<td>10 Hz</td>
<td>&lt;-87 dBc/Hz</td>
<td>&lt;-85 dBc/Hz</td>
</tr>
<tr>
<td>100 Hz</td>
<td>&lt;-114 dBc/Hz</td>
<td>&lt;-112 dBc/Hz</td>
</tr>
<tr>
<td>1 kHz</td>
<td>&lt;-130 dBc/Hz</td>
<td>&lt;-130 dBc/Hz</td>
</tr>
<tr>
<td>10 kHz</td>
<td>&lt;-140 dBc/Hz</td>
<td>&lt;-140 dBc/Hz</td>
</tr>
</tbody>
</table>

• Spurious (non-harmonic) <-85 dBc

### Temperature Coefficient (Peak-to-Peak)

<table>
<thead>
<tr>
<th>Temperature</th>
<th>SA.35m</th>
<th>SA.33m</th>
<th>SA.31m</th>
</tr>
</thead>
<tbody>
<tr>
<td>0 °C to 70 °C</td>
<td>&lt;7 x 10^-11</td>
<td>&lt;1 x 10^-10</td>
<td>&lt;7 x 10^-10</td>
</tr>
<tr>
<td>-10 °C to 75 °C</td>
<td>&lt;1 x 10^-10</td>
<td>&lt;1.5 x 10^-10</td>
<td>&lt;1 x 10^-9</td>
</tr>
</tbody>
</table>

### Aging

<table>
<thead>
<tr>
<th>Type</th>
<th>SA.35m/SA.33m</th>
<th>SA.31m</th>
</tr>
</thead>
<tbody>
<tr>
<td>Daily^2</td>
<td>±2.5 x 10^-11</td>
<td>±4 x 10^-11</td>
</tr>
<tr>
<td>Monthly^2</td>
<td>±1 x 10^-10</td>
<td>±3 x 10^-10</td>
</tr>
<tr>
<td>Yearly</td>
<td>±1 x 10^-9</td>
<td>±1.5 x 10^-9</td>
</tr>
</tbody>
</table>

^2 After 1 day and 1 month of operation, respectively.

### Short-Term Stability (Allan Deviation)

<table>
<thead>
<tr>
<th>Type</th>
<th>SA.35m/SA.33m</th>
<th>SA.31m</th>
</tr>
</thead>
<tbody>
<tr>
<td>t = 1 s</td>
<td>&lt;3 x 10^-11</td>
<td>&lt;5 x 10^-11</td>
</tr>
<tr>
<td>t = 10 s</td>
<td>&lt;1.6 x 10^-11</td>
<td>&lt;2.5 x 10^-11</td>
</tr>
<tr>
<td>t = 100 s</td>
<td>&lt;8 x 10^-12</td>
<td>&lt;1 x 10^-11</td>
</tr>
</tbody>
</table>

### Physical

- **Weight**: <85 g (<3 oz)
- **Size**: 18.3 mm × 50.8 mm × 50.8 mm
- **Volume**: <49.5 cm^3 (< 3.0 in^3)

### RoHS Compliance

- 6/6 RoHS-compliant

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